SOD323 SILICON HIGH CURRENT SCHOTTKY BARRIER DIODE "SuperBAT"

FEATURES

- Low V_F
- High current capability
- Miniature surface mount package

APPLICATIONS

- DC DC converters
- Mobile telecomms
- PCMCIA

DEVICE MARKING

• Partmark detail - BD

SOD323



PINOUT - TOP VIEW



Partmark is for example only

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Continuous Reverse Voltage	V _R	40	V
Forward Current (Continuous)	I _F	400	mA
Forward Voltage @ I _F =400mA	V _F	500	mV
Average Peak Forward Current; D.C. = 50%	I _{FAV}	1000	mA
Non Repetitive Forward Current $t \le 100 \mu s$ $t \le 10 ms$	I _{FSM}	6.75 3	A
Power Dissipation at T _{amb} =25°C	P _{tot}	250	mW
Storage Temperature Range	T _{stg}	-55 to +150	°C
Junction Temperature	T _j	125	°C

ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated)

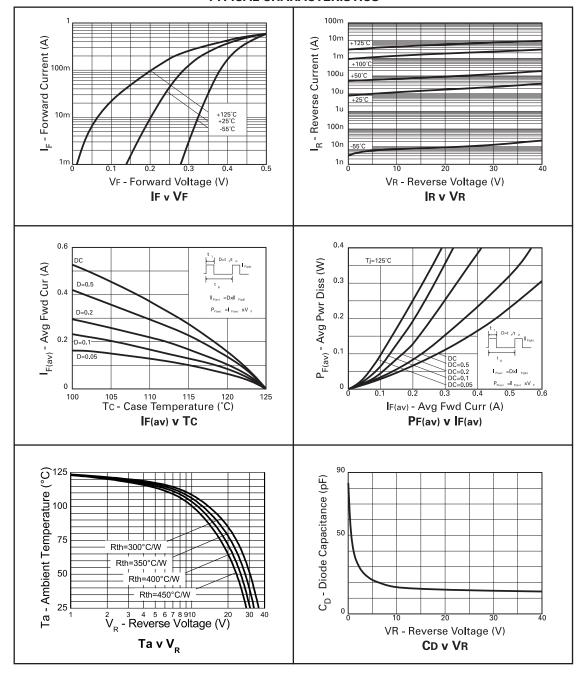
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reverse Breakdown Voltage	V _{(BR)R}	40	60		V	I _R =200μA
Forward Voltage	V _F		270 300 370 425 550 640 810 440	300 350 460 500 670 780 1050	mV mV mV mV mV mV	I _F =50mA I _F =100mA I _F =250mA I _F =400mA I _F =750mA I _F =1500mA I _F =500mA, T _{amb} =100°C
Reverse Current	I _R	5 773	15	40	μΑ	V _R =30V
Diode Capacitance	C _D	CON	20		pF	f=1MHz,V _R =25V
Reverse Recovery Time	t _{rr.} 0.75		10		ns	switched from $I_F = 500 \text{mA}$ Measured at $I_R = 50 \text{mA}$

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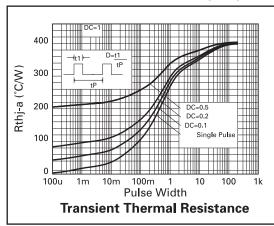


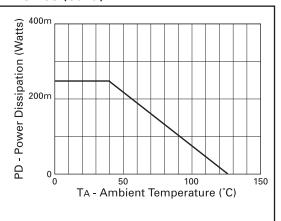
TYPICAL CHARACTERISTICS





TYPICAL CHARACTERISTICS (Cont.)







NOTES:



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or

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Product status key:

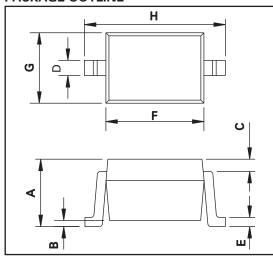
- "Preview"Future device intended for production at some point. Samples may be available
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- "Not recommended for new designs"Device is still in production to support existing designs and production
- "Obsolete"Production has been discontinued

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PACKAGE OUTLINE



PACKAGE DIMENSIONS

DIM	Millimeters		DIM	Millimeters		
DIIVI	Min	Max	DIIVI	Min	Max	
Α	0.91	1.16	Е	0.127	0.2	
В	-	0.1	F	1.52	1.77	
С	-	-	G	1.11	1.37	
D	0.33	0.4	Н	2.46	2.71	

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